

NCE N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

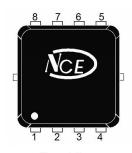
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

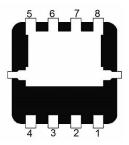
General Features

- V_{DS} =30V, I_{D} =70A $R_{DS(ON)}$ =1.65mΩ (typical) @ V_{GS} =10V $R_{DS(ON)}$ =2.1mΩ (typical) @ V_{GS} =4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

DFN 3.3X3.3





S1 S2 S3 G4

Top View

Bottom View

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P020N30BQU	NCEP020N30BQU	DFN3.3X3.3-8L	_	-	-

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G s	±12	V
Drain Current-Continuous	I _D	70	А
Drain Current-Continuous(T _C =100 ℃)	I _D (100℃)	55	А
Pulsed Drain Current	I _{DM}	280	А
Maximum Power Dissipation	P _D	55	W
Derating factor		0.44	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	352	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	Rejc	2.3	°C/W
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NCEP020N30BQU

Electrical Characteristics (T_C=25°C unless otherwise noted)

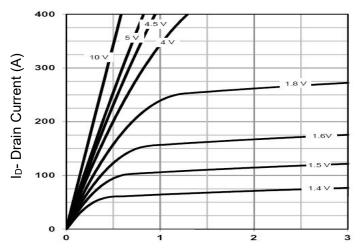
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.5	0.75	1.0	V
-i- C On Otata Basistana	Б	V _{GS} =10V, I _D =35A	-	1.65	2.0	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =35A	-	2.1	3.3	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =35A		65	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	3200	-	PF
Output Capacitance	Coss	V_{DS} =15 V , V_{GS} =0 V , F=1.0MHz	-	1600	-	PF
Reverse Transfer Capacitance	Crss	F-1.UIVITZ	-	115	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	6	-	nS
Turn-on Rise Time	t _r	V_{DD} =15 V , I_D =35 A	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	30	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	62	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =35A,	-	5.5		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	5.6		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =35A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	70	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = I _S	-	15	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	22	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=20V,VG=10V,L=0.5mH,Rg=25 Ω

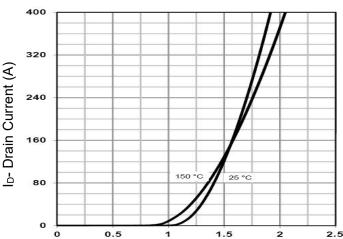


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)





Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

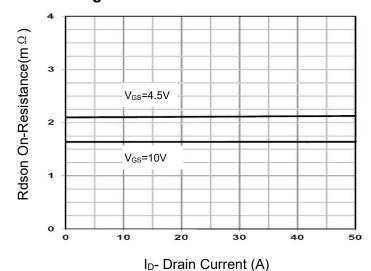
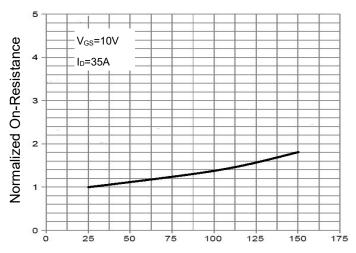


Figure 3 Rdson- Drain Current



T_J-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature

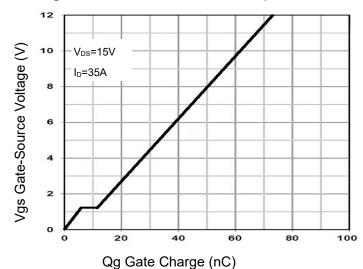
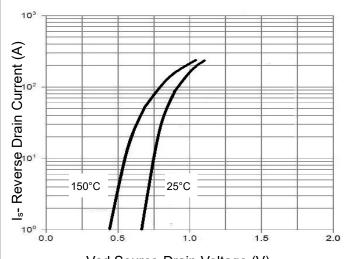


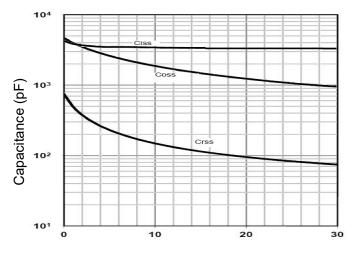
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

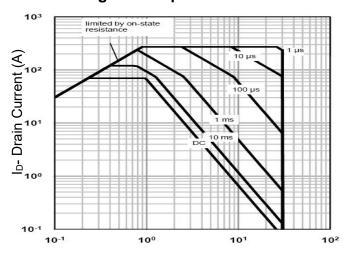
Figure 6 Source- Drain Diode Forward





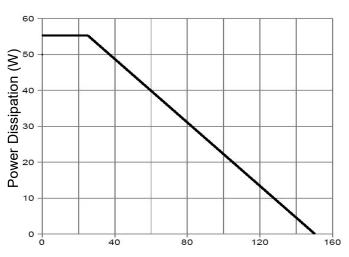
Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds



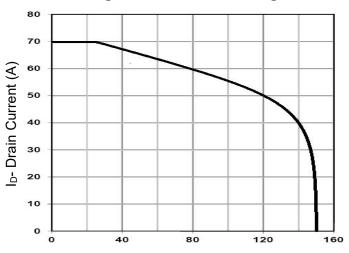
Vds Drain-Source Voltage (V)

Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)

Figure 9 Power De-rating



T_J-Junction Temperature (°C) **Figure 10 Current De-rating**

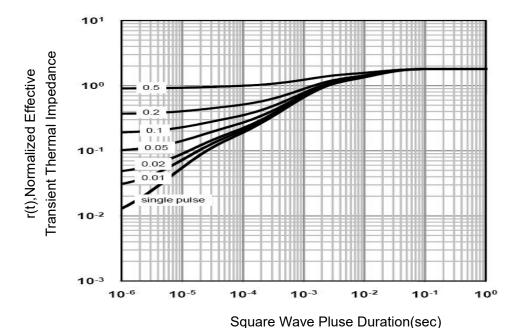
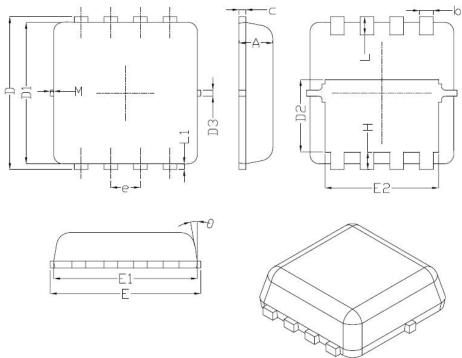


Figure 11 Normalized Maximum Transient Thermal Impedance

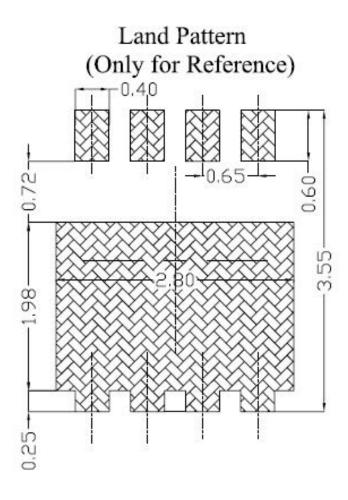


DFN3.3X3.3-8L Package Information



Symbol	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
С	0.10	0.15	0.25		
D	3.25	3.35	3.45		
D1	3.00	3.10	3.20		
D2	1.48	1.58	1.68		
D3	-	0.13	-		
E	3.20	3.30	3.40		
E1	3.00	3.15	3.20		
E2	2.39	2.49	2.59		
е	0.65BSC				
Н	0.30	0.39	0.50		
L	0.30	0.40	0.50		
L1	-	0.13	-		
М	*	*	0.15		
θ		10°	12 [°]		





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NCEP020N30BQU

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